



Final Product/Process Change Notification
 Document #:FPCN22647XBF
 Issue Date:17 Dec 2021

Title of Change:	Mold Compound Change attributed to an End of Life of Samsung SDI EMC for TO247 in SHEDCL	
Proposed First Ship date:	30 Mar 2022 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Yuna.Im@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Lalan.Ortega@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	No change of Marking of Parts / Traceability of Change	
Change Category:	Assembly Change	
Change Sub-Category(s):	Material Change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
None	SHANTOU HUASHAN Electronic Devices Co., Ltd., China	
Description and Purpose:		
onsemi wishes to inform a change in mold compounds used for the devices listed in this PCN. This is the final product change notification (FPCN). This change is a result of an End of Life notification received from Samsung for several of their SDI Mold Compounds. Due to the discontinuance of the SDI mold compounds, onsemi will only have limited supplies of the existing material.		
	Before Change Description	After Change Description
Mold compound	SDISG8200DL, Supplier: Samsung SDI	KTMC1050GFA-H, Supplier KCC Corporation
There is no product marking change as a result of this change.		



Reliability Data Summary:

QV DEVICE NAME: FCH76N60N
RMS: U79143, V79192, O78032
PACKAGE: TO-247

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0 / 231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0 / 231
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0 / 231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5.0 min	6000 Cyc	0 / 120
TC	JESD22-A104	Ta= -55°C to +150°C	1000 Cyc	0 / 231
H3TRB	JESD22 A101	Ta = 85°C, 85% RH, V=80% rated V	1008 hrs	0/231
AC	JESD22-A102	121°C, 100% RH, 15.5psig, unbiased	96 hrs	0 / 231
DPA	AEC Q101-004 Section 4	Following TC	1008 hrs	0 / 6
DPA	AEC Q101-004 Section 4	Following H3TRB	1008 hrs	0 / 6
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90
SD	JSTD002	Ta = 245C, 5 sec		0/45
PD	JESD22-B100B	Per POD, case outline		0/30
SAT	J-STD-035	Delamination	0hr	0 / 30
ED / CZ	Electrical Distribution / Characterization	Tri Temperature, Per 48A	0 hr	0 / 900
TR	JESD-24-3, 24-4, 24-6 as appropriate	per device specification, pre & post process change	0 hr	0 / 30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FCH104N60	FCH76N60N
FCH110N65F-F155	FCH76N60N
FCH130N60	FCH76N60N
FCH170N60	FCH76N60N
FCH190N65F-F155	FCH76N60N
FCH22N60N	FCH76N60N
FCH25N60N	FCH76N60N



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FCH35N60	FCH76N60N
FCH47N60-F133	FCH76N60N
FCH47N60F-F133	FCH76N60N
FCH47N60N	FCH76N60N
FCH47N60NF	FCH76N60N
FCH041N60F	FCH76N60N
FCH072N60	FCH76N60N
FCH043N60	FCH76N60N
FCH041N60E	FCH76N60N
FCH76N60N	FCH76N60N